

Data Sheet Comparison

▶ Old Material Set specification

Table 20. Simulated Thermal Resistance¹

PCB Type	Airflow Velocity (m/sec)	θ_{JA}	θ_{JC_TOP}	θ_{JB}	Unit
JEDEC 2s2p Board	0.0	11.7	0.40	2.3	°C/W

¹ Thermal resistance values specified are simulated based on JEDEC specifications in compliance with JESD51-12 with the device power equal to 9 W.

▶ New Material Set specification

Table 13. Simulated Thermal Resistance¹

PCB Type	Airflow Velocity (m/sec)	θ_{JA}	θ_{JC_TOP}	θ_{JB}	Unit
JEDEC 2s2p Board	0.0	14.9	0.70	1.8	°C/W

¹ Thermal resistance values specified are simulated based on JEDEC specifications in compliance with JESD51-12 with the device power equal to 9 W.